

1. General description

Planar passivated very sensitive gate four quadrant triac in a TO92 plastic package intended for use in applications requiring direct interfacing to logic ICs and low power gate drivers.

2. Features and benefits

- High blocking voltage capability
- Very sensitive gate
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drive circuits

3. Applications

- Industrial process control
- General purpose low power motor control
- Home appliances
- Low power AC Fan controllers

4. Quick reference data

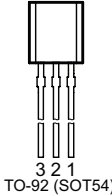
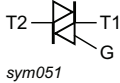
Table 1. Quick reference data

| Symbol | Parameter | Conditions | Notes | Values | | | Unit |
|--------------------------------|--------------------------------------|--|-------|------------|-----|-----|------|
| Absolute maximum rating | | | | | | | |
| V_{DRM} | repetitive peak off-state voltage | | | 800 | | | V |
| $I_{T(RMS)}$ | RMS on-state current | full sine wave; $T_{lead} \leq 66\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3 | | 1 | | | A |
| I_{TSM} | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig. 4 ; Fig. 5 | | 11 | | | A |
| | | full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 16.7\text{ ms}$ | | 12.1 | | | A |
| T_j | operating junction temperature | | | -40 to 125 | | | °C |
| Symbol | Parameter | Conditions | Notes | Min | Typ | Max | Unit |
| Static characteristics | | | | | | | |
| I_{GT} | gate trigger current | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G+; $T_j = 25\text{ °C}$; Fig. 7 | | - | - | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G-; $T_j = 25\text{ °C}$; Fig. 7 | | - | - | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G-; $T_j = 25\text{ °C}$; Fig. 7 | | - | - | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G+; $T_j = 25\text{ °C}$; Fig. 7 | | - | - | 10 | mA |

| Symbol | Parameter | Conditions | Notes | Min | Typ | Max | Unit |
|--------------------------------|---------------------------------------|---|-------|-----|-----|-----|------------|
| Static characteristics | | | | | | | |
| I_H | holding current | $V_D = 12\text{ V}; T_j = 25\text{ °C};$ Fig. 9 | | - | - | 10 | mA |
| V_T | on-state voltage | $I_T = 1\text{ A}; T_j = 25\text{ °C};$ Fig. 10 | | - | 1.3 | 1.5 | V |
| Dynamic characteristics | | | | | | | |
| dV_D/dt | rate of rise of off-state voltage | $V_{DM} = 536\text{ V}; T_j = 125\text{ °C};$ ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit | | 100 | - | - | V/ μ s |
| dV_{com}/dt | rate of change of commutating voltage | $V_D = 400\text{ V}; T_j = 125\text{ °C};$ $dI_{com}/dt = 0.5\text{ A/ms};$ gate open circuit | | 0.5 | - | - | V/ μ s |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-----------------|---|--|
| 1 | T2 | main terminal 2 |  <p>TO-92 (SOT54)</p> |  <p>sym051</p> |
| 2 | G | gate | | |
| 3 | T1 | main terminal 1 | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package Name | Orderable part number | Packing method | Small packing quantity | Package version | Package issue date |
|-------------|--------------|-----------------------|----------------|------------------------|-----------------|--------------------|
| BT231-800D | TO92 | BT231-800D,412 | Bulk | 1000 | TO92L | 10-May-2021 |

7. Marking

Table 4. Marking codes

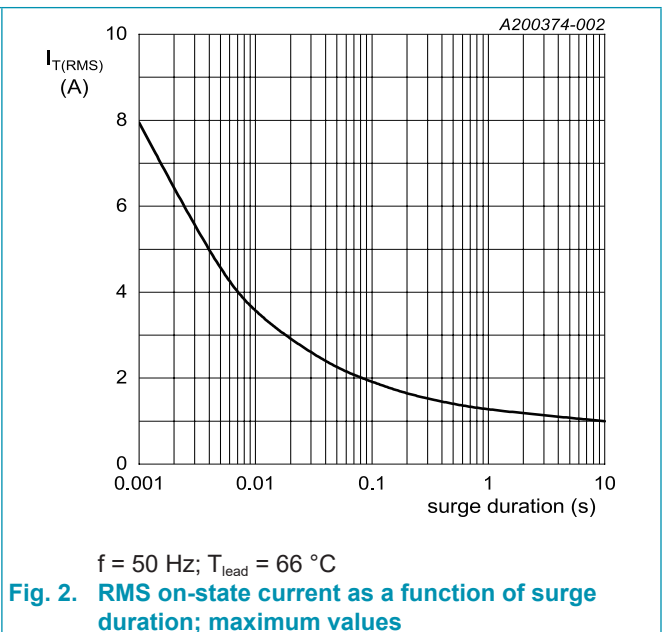
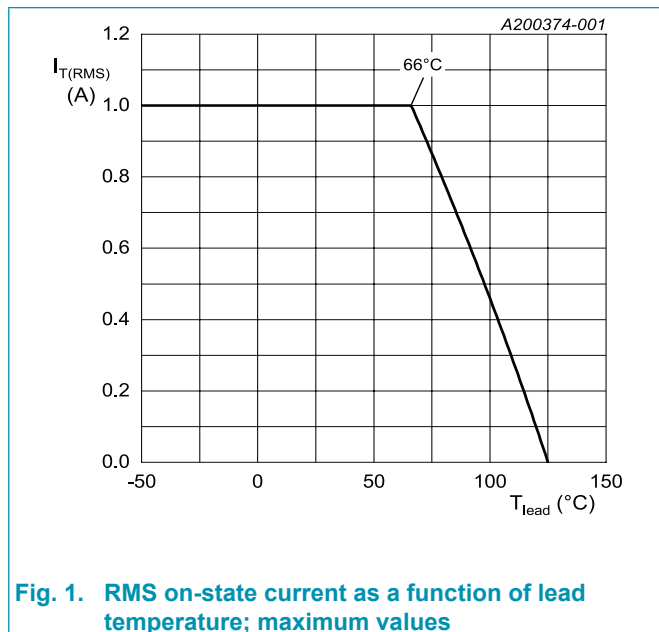
| Type number | Marking codes |
|-------------|---------------|
| BT231-800D | 231-8D |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Notes | Values | Unit |
|--------------|--------------------------------------|--|-------|------------|------------------|
| V_{DRM} | repetitive peak off-state voltage | | | 800 | V |
| V_{RRM} | repetitive peak reverse voltage | | | 800 | V |
| $I_{T(RMS)}$ | RMS on-state current | full sine wave; $T_{sp} \leq 66\text{ °C}$; Fig 1 ; Fig 2 ; Fig 3 | | 1 | A |
| I_{TSM} | non-repetitive peak on-state current | full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig 4 ; Fig 5 | | 11 | A |
| | | full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 16.7\text{ ms}$ | | 12.1 | A |
| I^2t | I^2t for fusing | $t_p = 10\text{ ms}$; SIN | | 0.6 | A ² s |
| di_T/dt | rate of rise of on-state current | $I_G = 10\text{ mA}$ | | 50 | A/ μ s |
| I_{GM} | peak gate current | | | 1 | A |
| P_{GM} | peak gate power | | | 2 | W |
| $P_{G(AV)}$ | average gate power | over any 20 ms period | | 0.1 | W |
| T_{stg} | storage temperature | | | -40 to 150 | °C |
| T_j | operating junction temperature | | | -40 to 125 | °C |



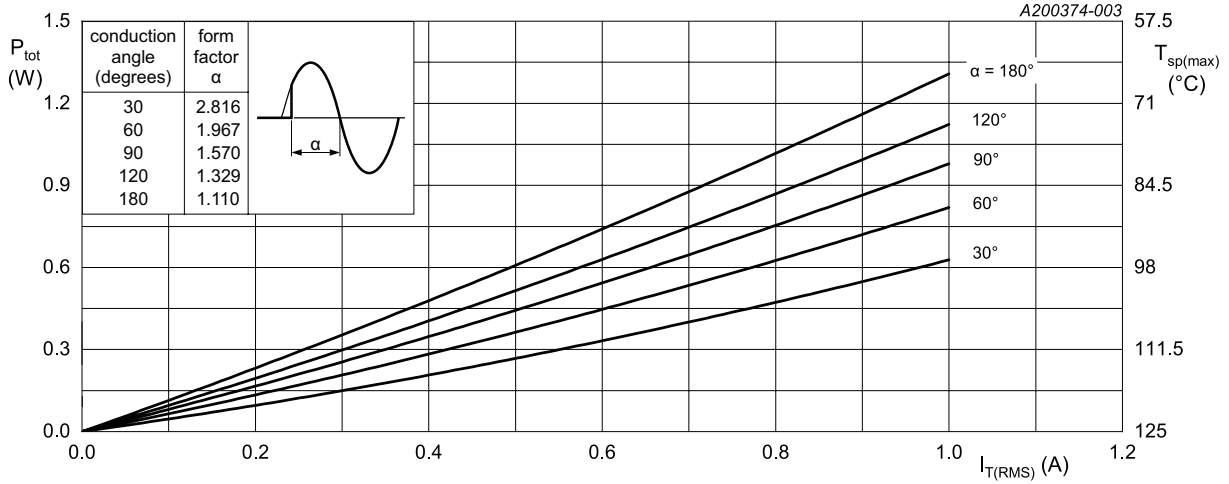
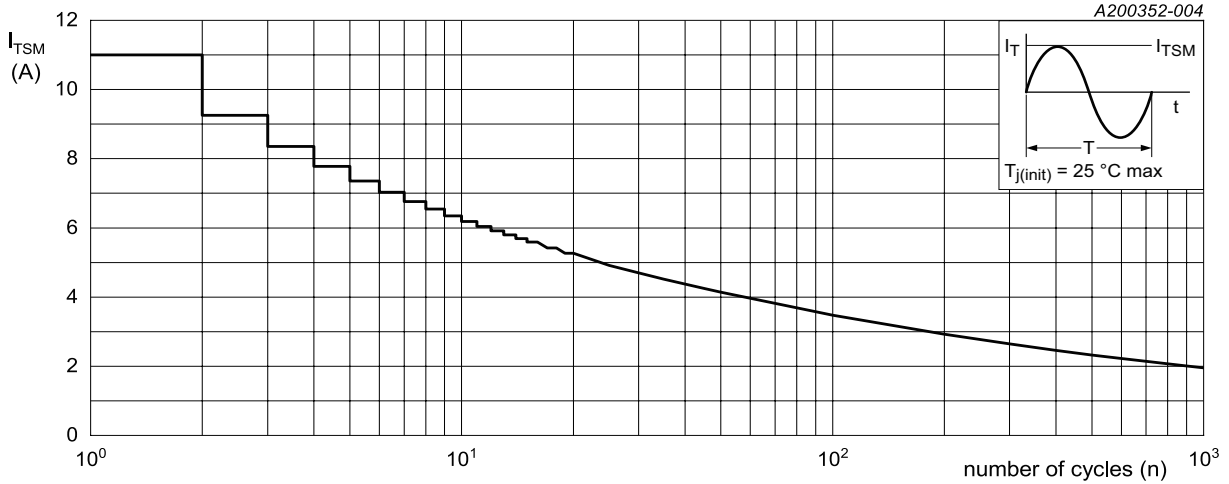
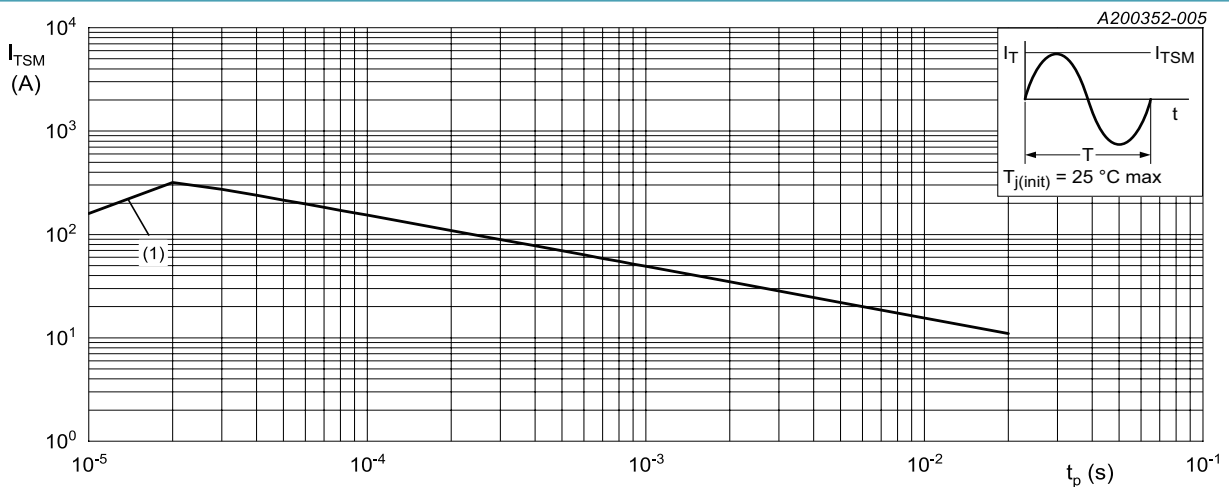


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



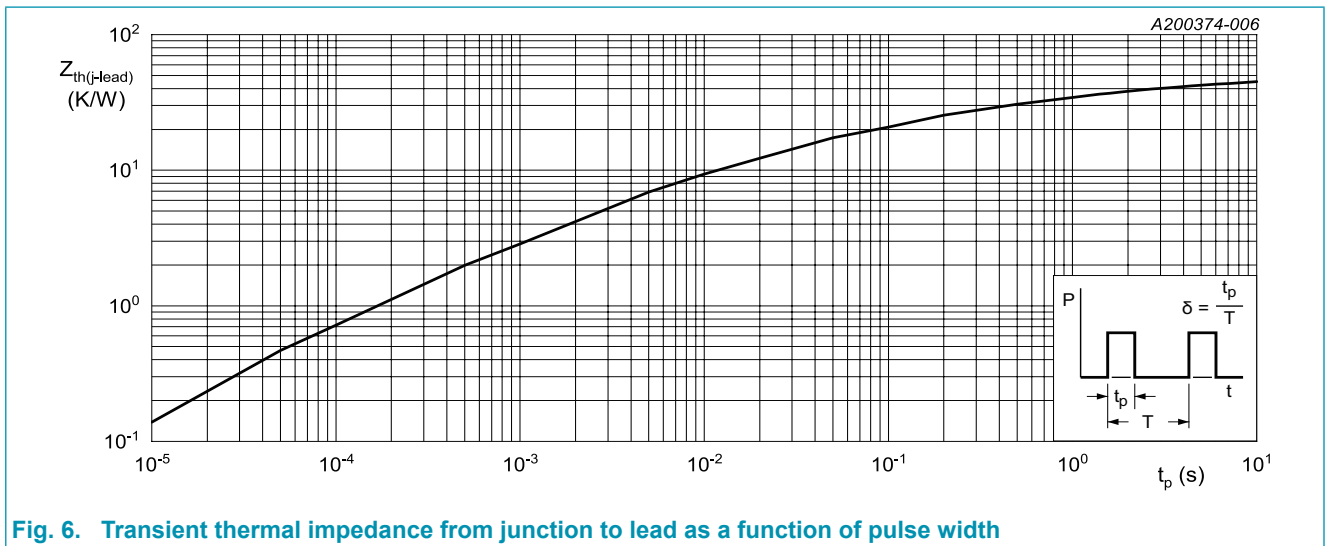
$t_p \leq 20$ ms
 (1) di_T/dt limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Notes | Min | Typ | Max | Unit |
|------------------|---|-----------------------|-------|-----|-----|-----|------|
| $R_{th(j-lead)}$ | thermal resistance from junction to lead | Fig 6 | | - | - | 45 | K/W |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | | - | 150 | - | K/W |



10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Notes | Min | Typ | Max | Unit |
|--------------------------------|---------------------------------------|---|-------|-----|-----|-----|------------------|
| Static characteristics | | | | | | | |
| I_{GT} | gate trigger current | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G+; $T_j = 25\text{ }^\circ\text{C}$; Fig. 7 | | - | - | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G-; $T_j = 25\text{ }^\circ\text{C}$; Fig. 7 | | - | - | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G-; $T_j = 25\text{ }^\circ\text{C}$; Fig. 7 | | - | - | 5 | mA |
| | | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G+; $T_j = 25\text{ }^\circ\text{C}$; Fig. 7 | | - | - | 10 | mA |
| I_L | latching current | $V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; T2+ G+; $T_j = 25\text{ }^\circ\text{C}$; Fig. 8 | | - | - | 10 | mA |
| | | $V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; T2+ G-; $T_j = 25\text{ }^\circ\text{C}$; Fig. 8 | | - | - | 10 | mA |
| | | $V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; T2- G-; $T_j = 25\text{ }^\circ\text{C}$; Fig. 8 | | - | - | 10 | mA |
| | | $V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; T2- G+; $T_j = 25\text{ }^\circ\text{C}$; Fig. 8 | | - | - | 20 | mA |
| I_H | holding current | $V_D = 12\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 9 | | - | - | 10 | mA |
| V_T | on-state voltage | $I_T = 1\text{ A}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 10 | | - | 1.3 | 1.5 | V |
| V_{GT} | gate trigger voltage | $V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 11 | | - | - | 1 | V |
| | | $V_D = 400\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 125\text{ }^\circ\text{C}$ | | 0.2 | - | - | V |
| I_D | off-state current | $V_D = 800\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$ | | - | - | 10 | μA |
| | | $V_D = 800\text{ V}$; $T_j = 125\text{ }^\circ\text{C}$ | | - | - | 0.5 | mA |
| I_R | reverse current | $V_R = 800\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$ | | - | - | 10 | μA |
| | | $V_R = 800\text{ V}$; $T_j = 125\text{ }^\circ\text{C}$ | | - | - | 0.5 | mA |
| Dynamic characteristics | | | | | | | |
| dV_D/dt | rate of rise of off-state voltage | $V_{DM} = 536\text{ V}$; $T_j = 125\text{ }^\circ\text{C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit | | 100 | - | - | V/ μs |
| dV_{com}/dt | rate of change of commutating voltage | $V_D = 400\text{ V}$; $T_j = 125\text{ }^\circ\text{C}$; $dI_{com}/dt = 0.5\text{ A/ms}$; gate open circuit | | 0.5 | - | - | V/ μs |

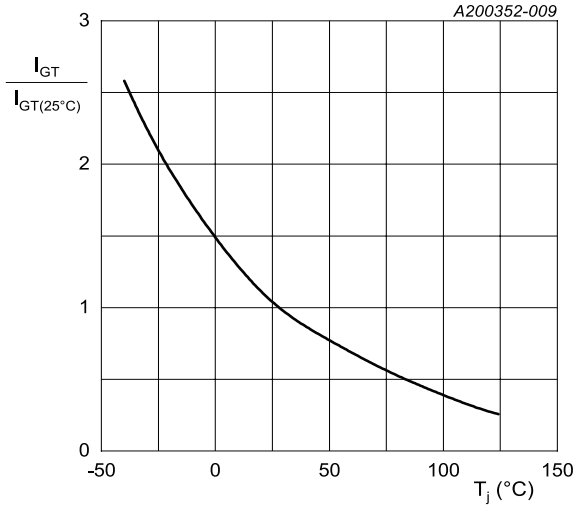


Fig. 7. Normalized gate trigger current as a function of junction temperature

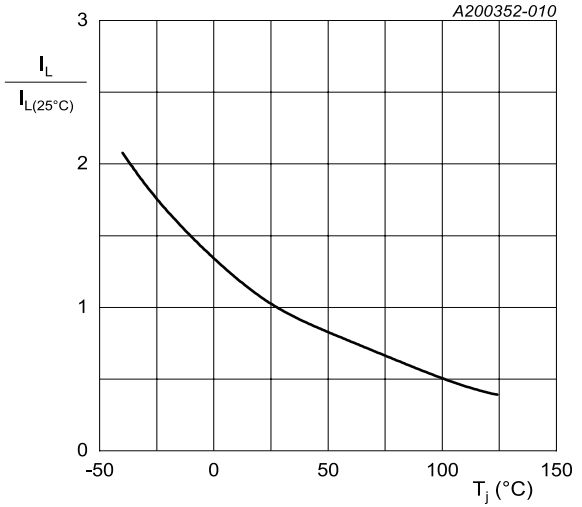


Fig. 8. Normalized latching current as a function of junction temperature

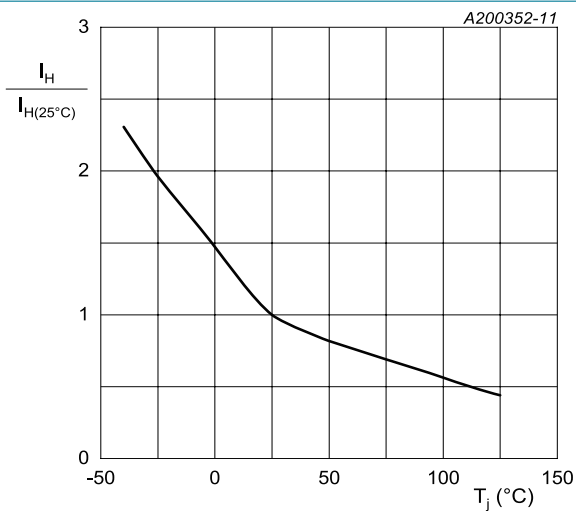
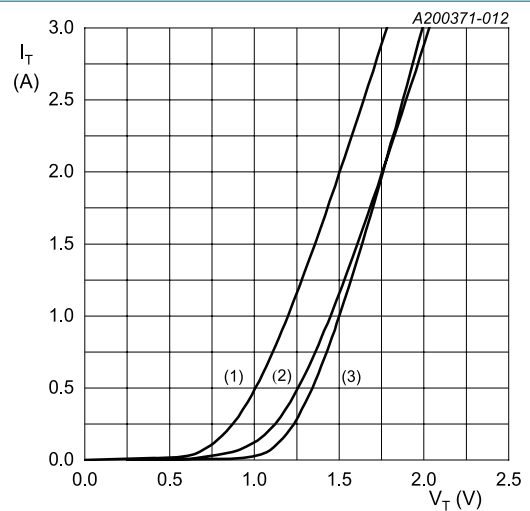


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.246 \text{ V}; R_s = 0.1850 \Omega$
 (1) $T_j = 125^\circ\text{C}$; typical values
 (2) $T_j = 125^\circ\text{C}$; maximum values
 (3) $T_j = 25^\circ\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

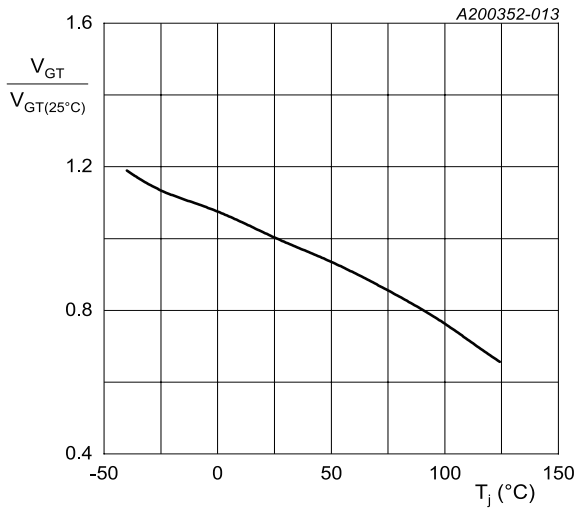
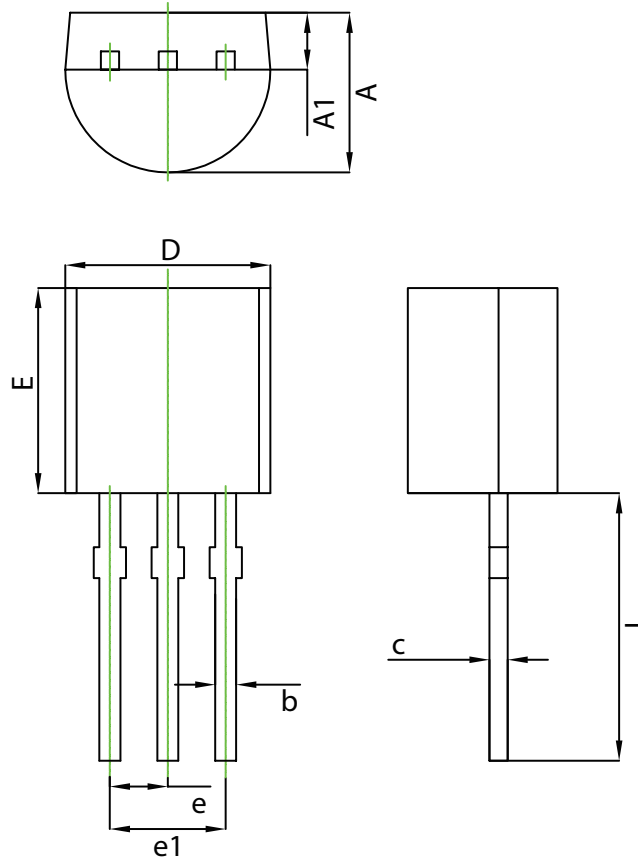


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

11. Package outline

Plastic single-ended leaded(through hole) package; 3 leads

TO92



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 3.300 | 3.700 | 0.130 | 0.146 |
| A1 | 1.100 | 1.400 | 0.043 | 0.055 |
| b | 0.380 | 0.550 | 0.015 | 0.022 |
| c | 0.360 | 0.510 | 0.014 | 0.020 |
| D | 4.300 | 4.700 | 0.169 | 0.185 |
| E | 4.300 | 4.700 | 0.169 | 0.185 |
| e | 1.270 TYP. | | 0.050 TYP. | |
| e1 | 2.440 | 2.640 | 0.096 | 0.104 |
| L | 14.100 | 14.500 | 0.555 | 0.571 |

12. Legal information

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|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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